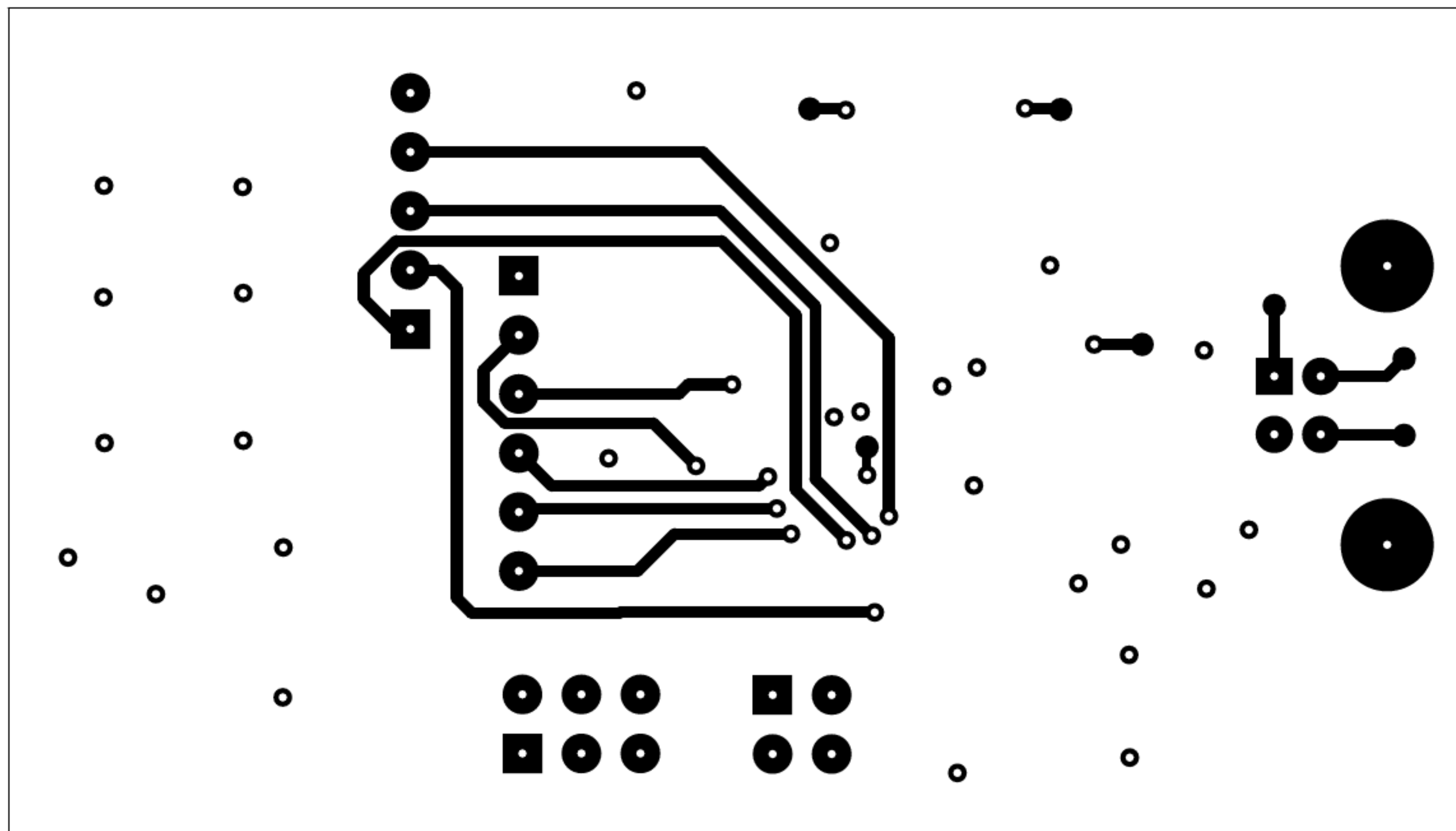Layer: F.Cu

Layer: In1.Cu

Layer: In2.Cu

Layer: F.Adhes (F.Adhesive)

Layer: F.Paste

Layer: B.SilkS (B.Silkscreen)

Layer: F.SilkS (F.Silkscreen)

R7 R6

Y1

J6 D3   D2   C4   C3   F1   J2

C8   U1   C7   R3   C6   VR2

J3   R5   R2   VR1

C5   R1

J1

+ C1   FB1

C2   J5   J4   R4   D1   JP1
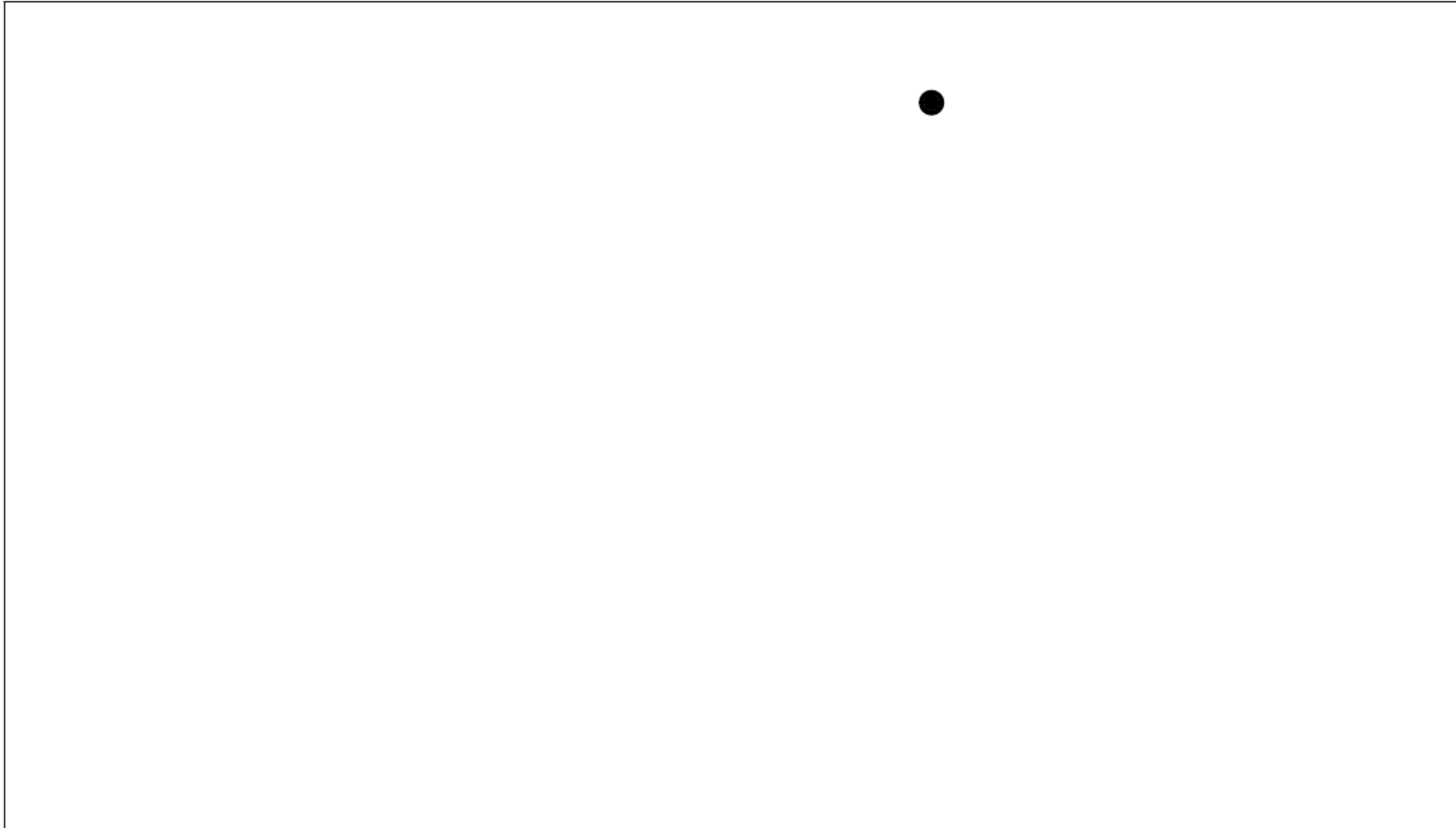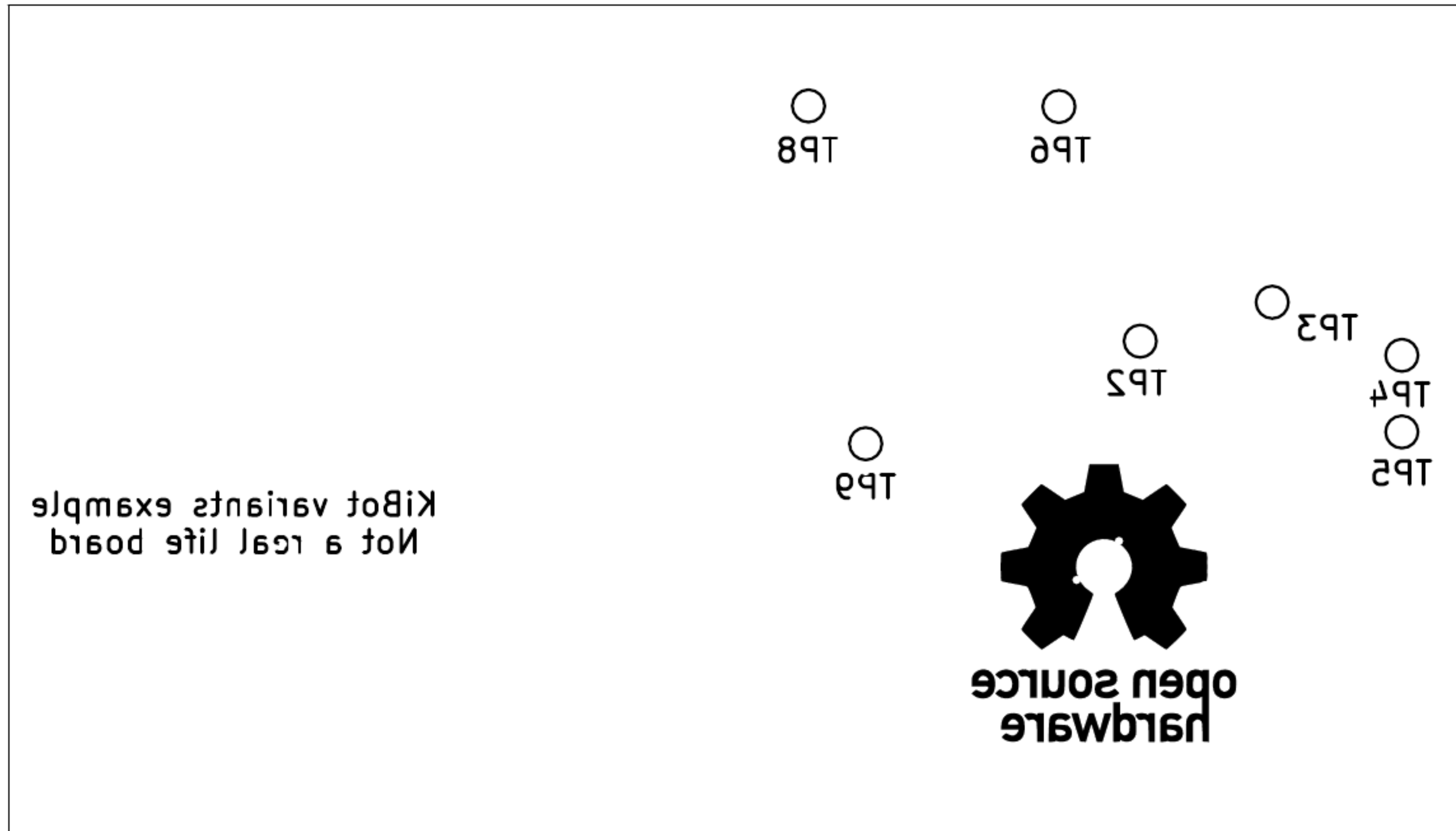
Layer: B.Mask

Layer: F.Mask

Layer: Dwgs.User (User.Drawings)

63.0010 mm

35.6156 mm

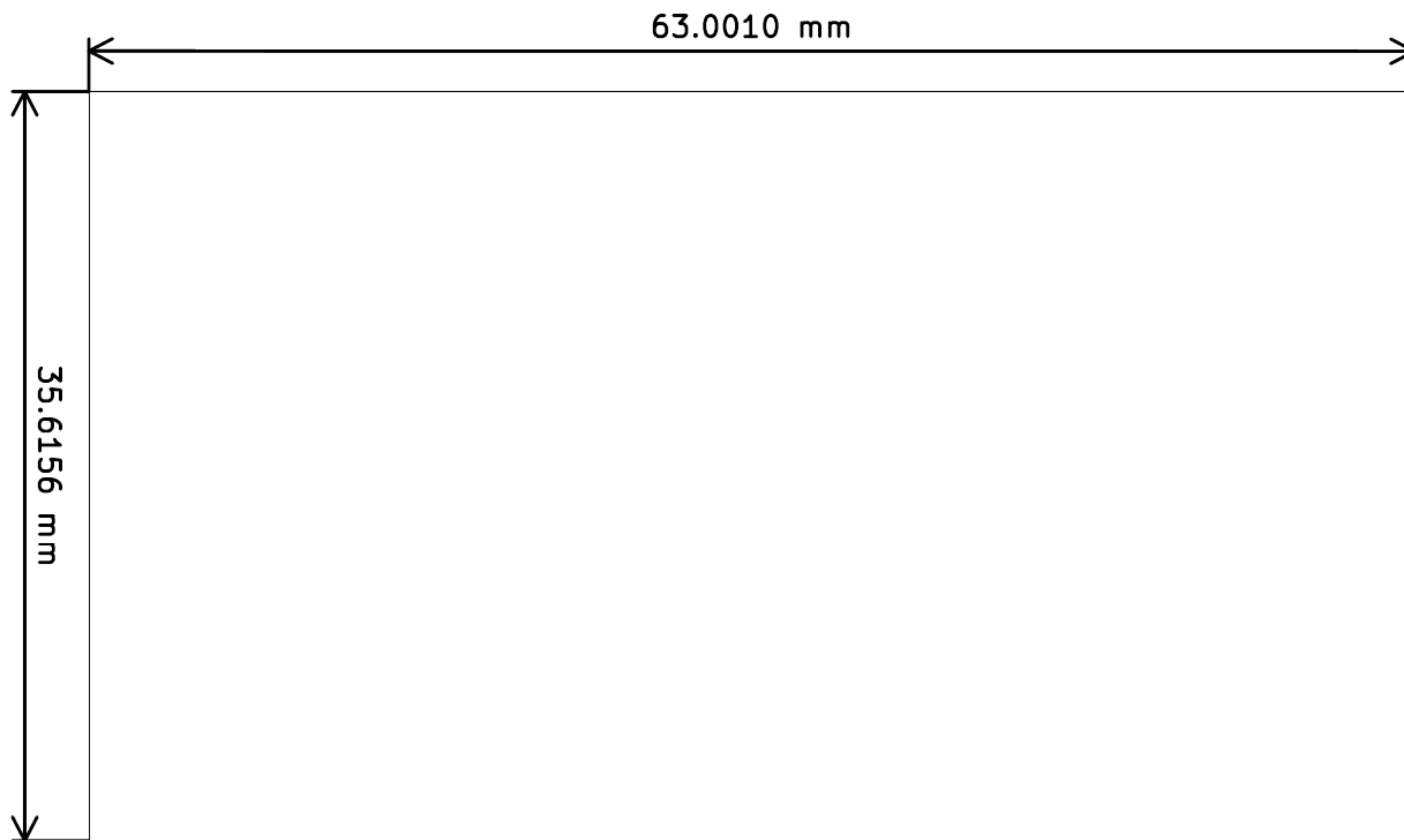Layer: Cmts.User (User.Comments)

Layer: Edge.Cuts

Layer: B.CrtYd (B.Courtyard)

Layer: F.CrtYd (F.Courtyard)

Layer: B.Fab

TestPoint

TP8

TestPoint

TP6

TestPoint

TP3

TestPoint

TP2

TestPoint

TP9

TestPoint

TP4

TestPoint

TP5

Layer: F.Fab

H3

Fiducial
FID3

MountingHole

P1

J3

1K 1K

R7 R6

LED

D3 D2

LED

C8 100nF

J6

R5

1K

C4

22pF

1M

R3

C7

100nF

16MHz

Y1

Fiducial
FID1

22pF

C3

100nF

C6

H4

MountingHole

MF-MSMF050-2

F1

CG0603MLC-05E

22R

R2

VR2

J2

U1

ATmega8U2-AU

P2

ICSP1

J5

C2

100nF

C1
47uF

H2

Fiducial
FID4

J4 2x2M

R4

10K

C5

1uF

R1

22R

VR1

CG0603MLC-05E

FB1

BLM21PG221SN1D

SolderJumper_2_Open

D1

CD1206-S01575

USB_B

Fiducial
FID2

H1

MountingHole

J1

Barrel_Jack_Switch

MountingHole